



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Shigeo OHSAKA et al.**

Serial No.: **09/456,531**

Filed: **December 8, 1999**

Group Art Unit: **2828**

Examiner: **James A. Mangfee**

P.T.O. Confirmation No.: **6582**

For: **ELECTRODE STRUCTURE, PROCESS FOR FABRICATING ELECTRODE STRUCTURE AND SEMICONDUCTOR LIGHT-EMITTING DEVICE**

**AMENDMENT UNDER 37 CFR §1.111**

Commissioner for Patents  
Washington, D.C. 20231

February 24, 2003

Sir:

In response to the Office Action dated **October 23, 2002**, extended to **February 23, 2003**, by a one month Petition for Extension of Time, please amend the above-identified application as follows:

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**CLEAN VERSION OF AMENDMENTS**

**IN THE CLAIMS:**

Please cancel claims 2, 5, 8-10, 12, 14 and 16 without prejudice or disclaimer.

Please amend claims 1, 3, 6, 7, 11 and 13, and add new claims 19-22, as follows:

1. (Twice Amended) An electrode structure including a bonding pad formed on an insulation film without penetrating the insulation film, the insulation film being formed above a base substrate,

the insulation film comprising a plurality of poles of polyimide, a first film formed on each